505992755 03/31/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6039465

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ZENTEL JAPAN CORPORATION	02/25/2020

RECEIVING PARTY DATA

Name:	HIROSHI WATANABE	
Street Address:	313, 689-1, TERAYAMACHO, MIDORI-KU	
City:	YOKOHAMA-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15638564

CORRESPONDENCE DATA

Fax Number: (908)518-7795

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 908-518-7700

Email: info@THELAWFIRM.CC
Correspondent Name: MAYER & WILLIAMS, P.C.

Address Line 1: 55 MADISON AVENUE, SUITE 400
Address Line 4: MORRISTOWN, NEW JERSEY 07960

ATTORNEY DOCKET NUMBER:	PF1586USC-S	
NAME OF SUBMITTER:	KARIN L. WILLIAMS	
SIGNATURE:	/Karin L. Williams/	
DATE SIGNED:	03/31/2020	

Total Attachments: 1

source=PF1586USC-S_Assignment#page1.tif

PATENT 505992755 REEL: 052271 FRAME: 0133

ASSIGNMENT

WHEREAS, WE, Zentel Japan Corporation, of 6-21-3, Shimbashi, Minato-ku, Tokyo, 105-0004, Japan, hereafter referred to as applicant, is the owner of all right, title and interest in the patent APPARATUS AND METHOD FOR CHIP IDENTIFICATION AND PREVENTING MALICIOUS MANIPULATION OF PHYSICAL ADDRESSES BY INCORPORATING A PHYSICAL NETWORK WITH A LOGICAL NETWORK for which U.S. Patent Application No. 15/638,564 was filed on June 30, 2017, and

WHEREAS, HIROSHI WATANABE, herein referred to as "Assignee", whose mailing address is 313, 689-1, Terayamacho, Midori-ku, Yokohama-shi, Kanagawa-ken, JAPAN, is desirous of acquiring the entire right, title and interest in and to said invention, and in and to and under any and all Letters Patent to be obtained thereon;

NOW, THEREFORE, for and in consideration of one Dollar (\$1.00) and other good and valuable considerations, the receipt of which is hereby acknowledged, we, the applicant, have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the Assignee, its successors and assigns the entire right, title and interest in and to said invention, said application and the Letters Patent, that may or shall issue.

Upon said consideration, we do hereby covenant and agree with the said Assignee, its successors and assigns, that we will not execute any writing or do any act whatsoever conflicting with these presents, and that we or our executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said Assignee, its successors and assigns, execute such additional writings and do such additional acts as said Assignee, its successors and assigns, may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Zentel Japan Corporation

Dated: February 25, 2020

By: Keiko Ko President

PATENT REEL: 052271 FRAME: 0134

RECORDED: 03/31/2020